EC - 705

B.E. VII Semester

Examination, December 2013

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VLSI Design

Time: Three Hours Maximum Marks: 70

Note: Attempt only one question from each unit. Each question carries equal marks

UNIT – I

- 1. a) Explain the operation ofn-channel enhancement MOSFET with different values of Gate voltage.
- b) What do you mean by hybrid technology? Describe the thick film and thin film circuits.

OR

- 2. a) Explain the following terms:
 - i) Oxidation
- ii) Lithography
- iii) Ion-Implantation
- iv) Epitaxy

b) Discuss about the Bipolar process in detail.

UNIT - II

- 3. a) Draw and explain small-signal MOSFET model.
- b) Explain short channel devices. Also mention its applications, advantages and limitations.

OR

- 4. a) Explain the dc model for(i) Diode (ii) BJT
- b) Explain the method for measurement of λ and K.

UNIT-III

- 5. a) Explain the simulation of a circuit using SPICE with suitable flowchart.
- b) Compare the high-frequency model of BJT and MOSSFET.

OR

6.a) Explain the level I large single MOSFET model.

b) Explain noise model for MOSFET as well as BJT.

UNIT-IV

- a) Explain and differentiate the random logic forms and stridulated logic forms.
- 14 Describe the Bit-serial processing elements in details.

OR

- 8. a) Discuss the working of a static register cell.
- b) What is Algotronix? Explain its architecture with detail.

UNIT- V

- 9. a) Discuss the steps of n-well CMOS fabrication process with suitable diagram.
- b) Explain the following tarns w ith respect to latch up:
 - i) Physical origin
 - ii) Latch-up prevention

OR

- 10. a) Explain the basic steps for the fabrication process flow
- b) What is the circuit elements? Describe the various type of circuit elements in detail.